Material Composition Declaration

EPC2091

Company Name	Efficient Power Conversion (EPC)	Issue Date:	8/19/2024
Contact Name:	Yanping Ma	Contact Title:	VP Quality
Contact Phone:	(310) 615-0280	Contact Email:	yanping.ma@epc-co.com
Part Weight:	12.5 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	10.7262	85.8826	89.5086	858826
	Silicon oxide	7631-86-9	0.0883	0.7073		7073
	Silicon nitride	12033-89-5	0.0255	0.2045		2045
	Gallium nitride	25617-97-4	0.0448	0.3590		3590
	Aluminum	7429-90-5	0.1375	1.1011		11011
	Aluminum nitride	24304-00-5	0.0069	0.0551		551
	Titanium	7440-32-6	0.0042	0.0335		335
	Titanium nitride	25583-20-4	0.0225	0.1798		1798
	Copper	7440-50-8	0.0023	0.0184		184
	Tungsten	7440-33-7	0.0113	0.0903		903
	Polyimide		0.1095	0.8770		8770
Under Bump Metal	Titanium	7440-32-6	0.0009	0.0073	0.0795	73
	Copper	7440-50-8	0.0090	0.0723		723
Solder Bump	Copper	7440-50-8	0.9025	7.2261	10.4118	72261
	Nickel	7440-02-0	0.0538	0.4311		4311
	Tin	7440-31-5	0.3378	2.7051		27051
	Silver	7440-22-4	0.0062	0.0496		496
Sum in total:			12.4894	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.